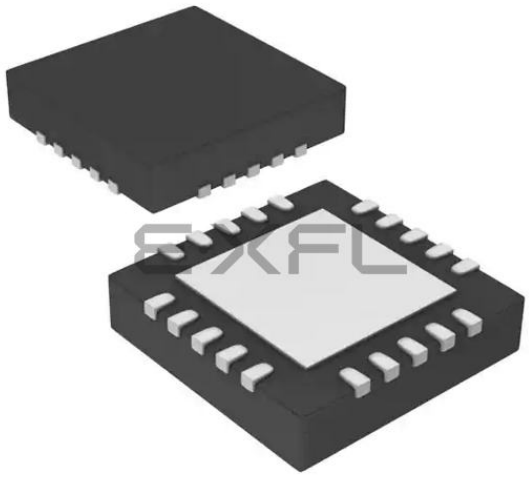

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	18
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-VFQFN Exposed Pad
Supplier Device Package	20-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f687-i-ml

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TABLE 1-1: PINOUT DESCRIPTION – PIC16F631 (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC6	RC6	ST	CMOS	General purpose I/O.
RC7	RC7	ST	CMOS	General purpose I/O.
VSS	VSS	Power	—	Ground reference.
VDD	VDD	Power	—	Positive supply.

Legend: AN = Analog input or output CMOS=CMOS compatible input or output
TTL = TTL compatible input ST= Schmitt Trigger input with CMOS levels
HV = High Voltage XTAL= Crystal

TABLE 2-3: PIC16F631/677/685/687/689/690 SPECIAL FUNCTION REGISTERS SUMMARY BANK 2

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Page
Bank 2											
100h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	43,200
101h	TMR0	Timer0 Module Register								xxxx xxxx	79,200
102h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	43,200
103h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	35,200
104h	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	43,200
105h	PORTA(4)	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	57,200
106h	PORTB(4)	RB7	RB6	RB5	RB4	—	—	—	—	xxxx ----	67,200
107h	PORTC(4)	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	74,200
108h	—	Unimplemented								—	—
109h	—	Unimplemented								—	—
10Ah	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	43,200
10Bh	INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF(1)	0000 000x	37,200
10Ch	EEDAT	EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0	0000 0000	118,201
10Dh	EEADR	EEADR7(3)	EEADR6	EEADR5	EEADR4	EEADR3	EEADR2	EEADR1	EEADR0	0000 0000	118,201
10Eh	EEDATH(2)	—	—	EEDATH5	EEDATH4	EEDATH3	EEDATH2	EEDATH1	EEDATH0	--00 0000	118,201
10Fh	EEADRH(2)	—	—	—	—	EEADRH3	EEADRH2	EEADRH1	EEADRH0	---- 0000	118,201
110h	—	Unimplemented								—	—
111h	—	Unimplemented								—	—
112h	—	Unimplemented								—	—
113h	—	Unimplemented								—	—
114h	—	Unimplemented								—	—
115h	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	—	—	—	—	1111 ----	68,201
116h	IOCB	IOCB7	IOCB6	IOCB5	IOCB4	—	—	—	—	0000 ----	68,201
117h	—	Unimplemented								—	—
118h	VRCON	C1VREN	C2VREN	VRR	VP6EN	VR3	VR2	VR1	VR0	0000 0000	103,201
119h	CM1CON0	C1ON	C1OUT	C1OE	C1POL	—	C1R	C1CH1	C1CH0	0000 -000	96,201
11Ah	CM2CON0	C2ON	C2OUT	C2OE	C2POL	—	C2R	C2CH1	C2CH0	0000 -000	97,201
11Bh	CM2CON1	MC1OUT	MC2OUT	—	—	—	—	T1GSS	C2SYNC	00-- --10	99,201
11Ch	—	Unimplemented								—	—
11Dh	—	Unimplemented								—	—
11Eh	ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3(3)	ANS2(3)	ANS1	ANS0	1111 1111	59,201
11Fh	ANSELH(3)	—	—	—	—	ANS11	ANS10	ANS9	ANS8	---- 1111	113,201

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: $\overline{MCLR}$ and WDT Reset does not affect the previous value data latch. The RABIF bit will be cleared upon Reset but will set again if the mismatch exists.

2: PIC16F685/PIC16F689/PIC16F690 only.

3: PIC16F677/PIC16F685/PIC16F687/PIC16F689/PIC16F690 only.

4: Port pins with analog functions controlled by the ANSEL and ANSELH registers will read '0' immediately after a Reset even though the data latches are either undefined (POR) or unchanged (other Resets).

9.2 ADC Operation

9.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/DONE bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note:	The GO/DONE bit should not be set in the same instruction that turns on the ADC. Refer to **Section 9.2.6 "A/D Conversion Procedure"**.

9.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/DONE bit
- Set the ADIF flag bit
- Update the ADRESH:ADRESL registers with new conversion result

9.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/DONE bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete Analog-to-Digital conversion sample. Instead, the ADRESH:ADRESL register pair will retain the value of the previous conversion. Additionally, a 2 TAD delay is required before another acquisition can be initiated. Following this delay, an input acquisition is automatically started on the selected channel.

Note:	A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

9.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

9.2.5 SPECIAL EVENT TRIGGER

An ECCP Special Event Trigger allows periodic ADC measurements without software intervention. When this trigger occurs, the GO/DONE bit is set by hardware and the Timer1 counter resets to zero.

Using the Special Event Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

See **Section 11.0 "Enhanced Capture/Compare/PWM Module"** for more information.

9.2.6 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (See TRIS register)
   - Configure pin as analog
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel
   - Select result format
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt**(1)**
4. Wait the required acquisition time**(2)**.
5. Start conversion by setting the GO/DONE bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/DONE bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1:	The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.
2:	See **Section 9.3 "A/D Acquisition Requirements"**.

10.0 DATA EEPROM AND FLASH PROGRAM MEMORY CONTROL

Data EEPROM memory is readable and writable and the Flash program memory (PIC16F685/PIC16F689/PIC16F690 only) is readable during normal operation (full V_{DD} range). These memories are not directly mapped in the register file space. Instead, they are indirectly addressed through the Special Function Registers (SFRs). There are six SFRs used to access these memories:

- EECON1
- EECON2
- EEDAT
- EEDATH (PIC16F685/PIC16F689/PIC16F690 only)
- EEADR
- EEADRH (PIC16F685/PIC16F689/PIC16F690 only)

When interfacing the data memory block, EEDAT holds the 8-bit data for read/write, and EEADR holds the address of the EEDAT location being accessed. These devices, except for the PIC16F631, have 256 bytes of data EEPROM with an address range from 0h to 0FFh. The PIC16F631 has 128 bytes of data EEPROM with an address range from 0h to 07Fh.

When accessing the program memory block of the PIC16F685/PIC16F689/PIC16F690 devices, the EEDAT and EEDATH registers form a 2-byte word that holds the 14-bit data for read/write, and the EEADR and EEADRH registers form a 2-byte word that holds the 12-bit address of the EEPROM location being read. These devices (PIC16F685/PIC16F689/PIC16F690) have 4K words of program EEPROM with an address range from 0h to 0FFFh. The program memory allows one-word reads.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write).

The write time is controlled by an on-chip timer. The write/erase voltages are generated by an on-chip charge pump rated to operate over the voltage range of the device for byte or word operations.

When the device is code-protected, the CPU may continue to read and write the data EEPROM memory and read the program memory. When code-protected, the device programmer can no longer access data or program memory.

10.1 EEADR and EEADRH Registers

The EEADR and EEADRH registers can address up to a maximum of 256 bytes of data EEPROM or up to a maximum of 4K words of program EEPROM.

When selecting a program address value, the MSB of the address is written to the EEADRH register and the LSB is written to the EEADR register. When selecting a data address value, only the LSB of the address is written to the EEADR register.

10.1.1 EECON1 AND EECON2 REGISTERS

EECON1 is the control register for EE memory accesses.

Control bit EEPGD (PIC16F685/PIC16F689/PIC16F690) determines if the access will be a program or data memory access. When clear, as it is when reset, any subsequent operations will operate on the data memory. When set, any subsequent operations will operate on the program memory. Program memory can only be read.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared in hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation to data EEPROM. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a $\overline{MCLR}$ or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit and rewrite the location.

Interrupt flag bit EEIF of the PIR2 register is set when write is complete. It must be cleared in the software.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the data EEPROM write sequence.

11.3.4 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCP1 pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

11.3.5 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency. Any changes in the system clock frequency will result in changes to the PWM frequency. See **Section 3.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for additional details.

11.3.6 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

11.3.7 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

1. Disable the PWM pin (CCP1) output driver by setting the associated TRIS bit.
2. Set the PWM period by loading the PR2 register.
3. Configure the CCP module for the PWM mode by loading the CCP1CON register with the appropriate values.
4. Set the PWM duty cycle by loading the CCPR1L register and DC1B<1:0> bits of the CCP1CON register.
5. Configure and start Timer2:
   - •Clear the TMR2IF interrupt flag bit of the PIR1 register.
   - •Set the Timer2 prescale value by loading the T2CKPS bits of the T2CON register.
   - •Enable Timer2 by setting the TMR2ON bit of the T2CON register.
6. Enable PWM output after a new PWM cycle has started:
   - •Wait until Timer2 overflows (TMR2IF bit of the PIR1 register is set).
   - Enable the CCP1 pin output driver by clearing the associated TRIS bit.

11.4 PWM (Enhanced Mode)

The Enhanced PWM Mode can generate a PWM signal on up to four different output pins with up to ten bits of resolution. It can do this through four different PWM Output modes:

- Single PWM
- Half-Bridge PWM
- Full-Bridge PWM, Forward mode
- Full-Bridge PWM, Reverse mode

To select an Enhanced PWM mode, the P1M bits of the CCP1CON register must be set appropriately.

The PWM outputs are multiplexed with I/O pins and are designated P1A, P1B, P1C and P1D. The polarity of the PWM pins is configurable and is selected by setting the CCP1M bits in the CCP1CON register appropriately.

Table 11-4 shows the pin assignments for each Enhanced PWM mode.

Figure 11-5 shows an example of a simplified block diagram of the Enhanced PWM module.

Note:	To prevent the generation of an incomplete waveform when the PWM is first enabled, the ECCP module waits until the start of a new PWM period before generating a PWM signal.

11.4.2 FULL-BRIDGE MODE

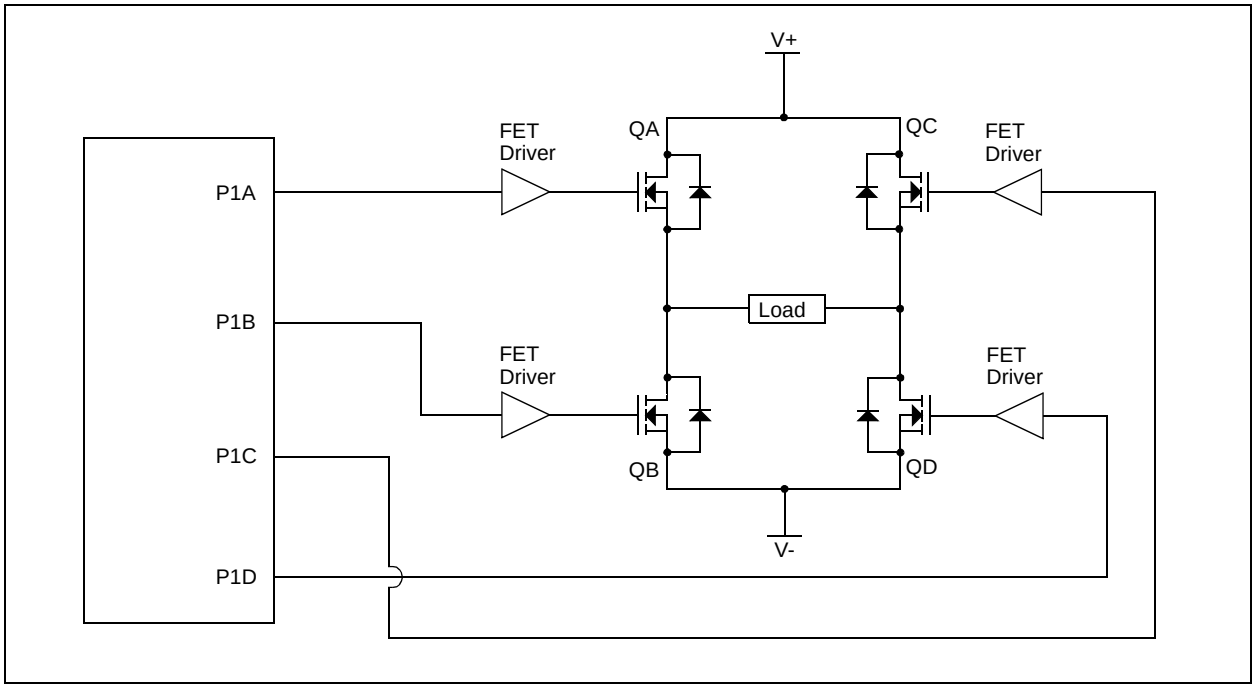
In Full-Bridge mode, all four pins are used as outputs. An example of Full-Bridge application is shown in Figure 11-10.

In the Forward mode, pin CCP1/P1A is driven to its active state, pin P1D is modulated, while P1B and P1C will be driven to their inactive state as shown in Figure 11-11.

In the Reverse mode, P1C is driven to its active state, pin P1B is modulated, while P1A and P1D will be driven to their inactive state as shown Figure 11-11.

P1A, P1B, P1C and P1D outputs are multiplexed with the PORT data latches. The associated TRIS bits must be cleared to configure the P1A, P1B, P1C and P1D pins as outputs.

FIGURE 11-10: EXAMPLE OF FULL-BRIDGE APPLICATION



12.1.2 EUSART ASYNCHRONOUS RECEIVER

The Asynchronous mode is typically used in RS-232 systems. The receiver block diagram is shown in Figure 12-2. The data is received on the RX/DT pin and drives the data recovery block. The data recovery block is actually a high-speed shifter operating at 16 times the baud rate, whereas the serial Receive Shift Register (RSR) operates at the bit rate. When all eight or nine bits of the character have been shifted in, they are immediately transferred to a two character First-In-First-Out (FIFO) memory. The FIFO buffering allows reception of two complete characters and the start of a third character before software must start servicing the EUSART receiver. The FIFO and RSR registers are not directly accessible by software. Access to the received data is via the RCREG register.

12.1.2.1 Enabling the Receiver

The EUSART receiver is enabled for asynchronous operation by configuring the following three control bits:

- CREN = 1
- SYNC = 0
- SPEN = 1

All other EUSART control bits are assumed to be in their default state.

Setting the CREN bit of the RCSTA register enables the receiver circuitry of the EUSART. Clearing the SYNC bit of the TXSTA register configures the EUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the EUSART and automatically configures the RX/DT I/O pin as an input. If the RX/DT pin is shared with an analog peripheral the analog I/O function must be disabled by clearing the corresponding ANSEL bit.

Note:	When the SPEN bit is set the TX/CK I/O pin is automatically configured as an output, regardless of the state of the corresponding TRIS bit and whether or not the EUSART transmitter is enabled. The PORT latch is disconnected from the output driver so it is not possible to use the TX/CK pin as a general purpose output.

12.1.2.2 Receiving Data

The receiver data recovery circuit initiates character reception on the falling edge of the first bit. The first bit, also known as the Start bit, is always a zero. The data recovery circuit counts one-half bit time to the center of the Start bit and verifies that the bit is still a zero. If it is not a zero then the data recovery circuit aborts character reception, without generating an error, and resumes looking for the falling edge of the Start bit. If the Start bit zero verification succeeds then the data recovery circuit counts a full bit time to the center of the next bit. The bit is then sampled by a majority detect circuit and the resulting '0' or '1' is shifted into the RSR. This repeats until all data bits have been sampled and shifted into the RSR. One final bit time is measured and the level sampled. This is the Stop bit, which is always a '1'. If the data recovery circuit samples a '0' in the Stop bit position then a framing error is set for this character, otherwise the framing error is cleared for this character. See **Section 12.1.2.4 "Receive Framing Error"** for more information on framing errors.

Immediately after all data bits and the Stop bit have been received, the character in the RSR is transferred to the EUSART receive FIFO and the RCIF interrupt flag bit of the PIR1 register is set. The top character in the FIFO is transferred out of the FIFO by reading the RCREG register.

Note:	If the receive FIFO is overrun, no additional characters will be received until the overrun condition is cleared. See ***Section 12.1.2.5 "Receive Overrun Error"*** for more information on overrun errors.

12.1.2.3 Receive Interrupts

The RCIF interrupt flag bit of the PIR1 register is set whenever the EUSART receiver is enabled and there is an unread character in the receive FIFO. The RCIF interrupt flag bit is read-only, it cannot be set or cleared by software.

RCIF interrupts are enabled by setting all of the following bits:

- RCIE interrupt enable bit of the PIE1 register
- PEIE peripheral interrupt enable bit of the INTCON register
- GIE global interrupt enable bit of the INTCON register

The RCIF interrupt flag bit will be set when there is an unread character in the FIFO, regardless of the state of interrupt enable bits.

TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	1221	1.73	255	1200	0.00	239	1200	0.00	143	1202	0.16	103
2400	2404	0.16	129	2400	0.00	119	2400	0.00	71	2404	0.16	51
9600	9470	-1.36	32	9600	0.00	29	9600	0.00	17	9615	0.16	12
10417	10417	0.00	29	10286	-1.26	27	10165	-2.42	16	10417	0.00	11
19.2k	19.53k	1.73	15	19.20k	0.00	14	19.20k	0.00	8	—	—	—
57.6k	—	—	—	57.60k	0.00	7	57.60k	0.00	2	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300	0.16	207	300	0.00	191	300	0.16	103	300	0.16	51
1200	1202	0.16	51	1200	0.00	47	1202	0.16	25	1202	0.16	12
2400	2404	0.16	25	2400	0.00	23	2404	0.16	12	—	—	—
9600	—	—	—	9600	0.00	5	—	—	—	—	—	—
10417	10417	0.00	5	—	—	—	10417	0.00	2	—	—	—
19.2k	—	—	—	19.20k	0.00	2	—	—	—	—	—	—
57.6k	—	—	—	57.60k	0.00	0	—	—	—	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	2404	0.16	207
9600	9615	0.16	129	9600	0.00	119	9600	0.00	71	9615	0.16	51
10417	10417	0.00	119	10378	-0.37	110	10473	0.53	65	10417	0.00	47
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35	19231	0.16	25
57.6k	56.82k	-1.36	21	57.60k	0.00	19	57.60k	0.00	11	55556	-3.55	8
115.2k	113.64k	-1.36	10	115.2k	0.00	9	115.2k	0.00	5	—	—	—

TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 20.000 MHz			FOSC = 18.432 MHz			FOSC = 11.0592 MHz			FOSC = 8.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	9215	300.0	0.00	6666
1200	1200	-0.01	4166	1200	0.00	3839	1200	0.00	2303	1200	-0.02	1666
2400	2400	0.02	2082	2400	0.00	1919	2400	0.00	1151	2401	0.04	832
9600	9597	-0.03	520	9600	0.00	479	9600	0.00	287	9615	0.16	207
10417	10417	0.00	479	10425	0.08	441	10433	0.16	264	10417	0	191
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.20k	0.00	143	19.23k	0.16	103
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.60k	0.00	47	57.14k	-0.79	34
115.2k	116.3k	0.94	42	115.2k	0.00	39	115.2k	0.00	23	117.6k	2.12	16

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 4.000 MHz			FOSC = 3.6864 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.01	3332	300.0	0.00	3071	299.9	-0.02	1666	300.1	0.04	832
1200	1200	0.04	832	1200	0.00	767	1199	-0.08	416	1202	0.16	207
2400	2398	0.08	416	2400	0.00	383	2404	0.16	207	2404	0.16	103
9600	9615	0.16	103	9600	0.00	95	9615	0.16	51	9615	0.16	25
10417	10417	0.00	95	10473	0.53	87	10417	0.00	47	10417	0.00	23
19.2k	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	25	19.23k	0.16	12
57.6k	58.82k	2.12	16	57.60k	0.00	15	55.56k	-3.55	8	—	—	—
115.2k	111.1k	-3.55	8	115.2k	0.00	7	—	—	—	—	—	—

12.3.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCTL register starts the auto-baud calibration sequence (Figure 12-6). While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Table 12-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRG register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRG register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 12-6. During ABD, both the SPBRGH and SPBRG registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRG registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 12.3.2 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

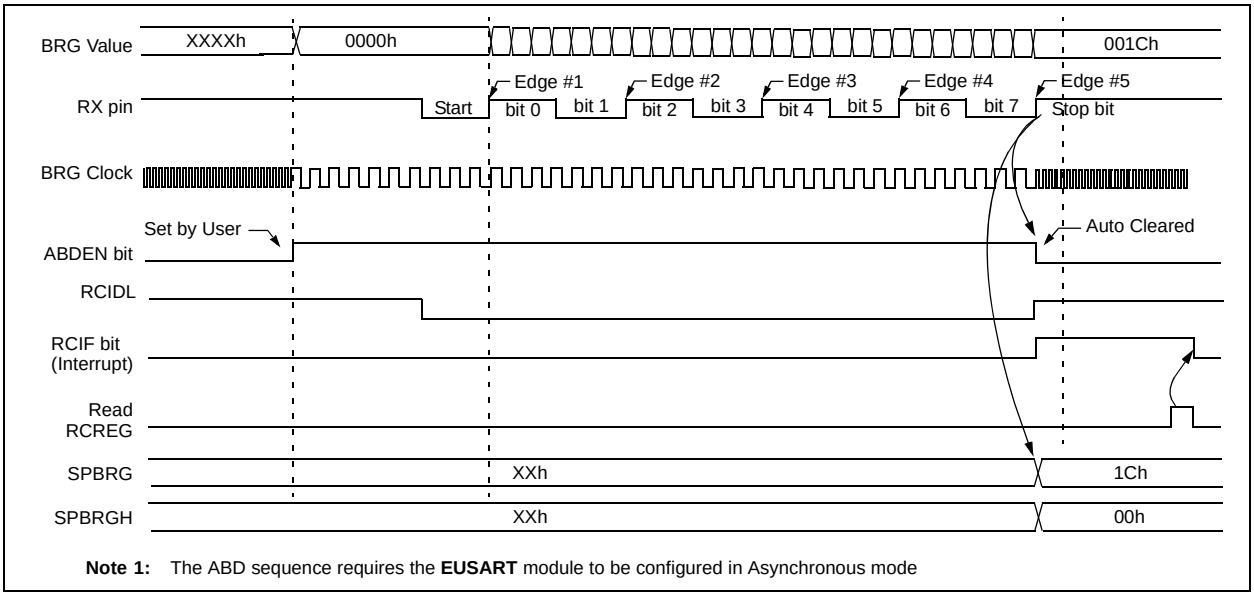
3: During the auto-baud process, the auto-baud counter starts counting at 1. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRG register pair.

TABLE 12-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SPBRG and SPBRGH registers are both used as a 16-bit counter, independent of BRG16 setting.

FIGURE 12-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode

FIGURE 13-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

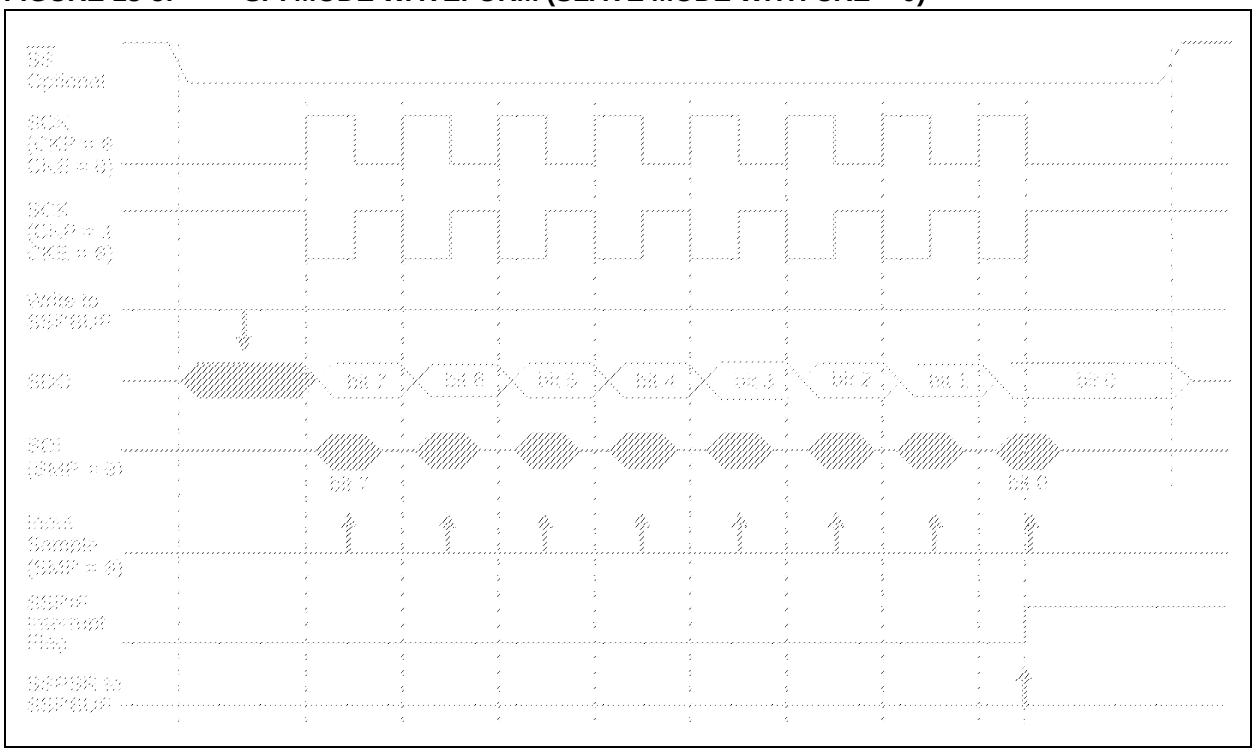


FIGURE 13-6: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)

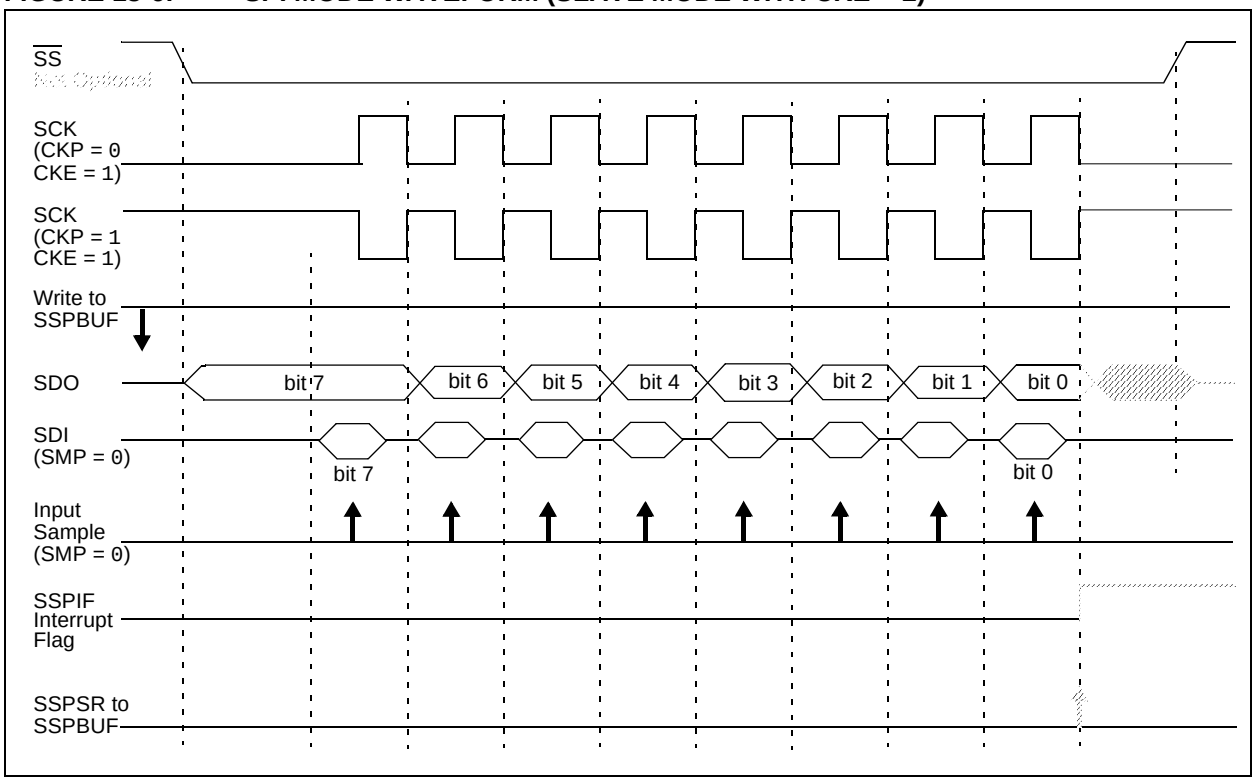


TABLE 17-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS06	TWARM	Internal Oscillator Switch when running(3)	—	—	—	2	TOSC	Slowest clock
OS07	TSC	Fail-Safe Sample Clock Period(1)	—	—	21	—	ms	LFINTOSC/64
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±1%	7.92	8.0	8.08	MHz	VDD = 3.5V, 25°C
			±2%	7.84	8.0	8.16	MHz	2.5V ≤ VDD ≤ 5.5V, 0°C ≤ TA ≤ +85°C
			±5%	7.60	8.0	8.40	MHz	2.0V ≤ VDD ≤ 5.5V, -40°C ≤ TA ≤ +85°C (Ind.), -40°C ≤ TA ≤ +125°C (Ext.)
OS09*	LFOSC	Internal Uncalibrated LFINTOSC Frequency	—	15	31	45	kHz	
OS10*	TIOSC ST	HFINTOSC Oscillator Wake-up from Sleep Start-up Time	—	5.5	12	24	µs	VDD = 2.0V, -40°C to +85°C
			—	3.5	7	14	µs	VDD = 3.0V, -40°C to +85°C
			—	3	6	11	µs	VDD = 5.0V, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at ‘min’ values with an external clock applied to the OSC1 pin. When an external clock input is used, the ‘max’ cycle time limit is ‘DC’ (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: By design.

TABLE 17-14: I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
100*	THIGH	Clock high time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10-400 pF
90*	TSU:STA	Start condition setup time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91*	THD:STA	Start condition hold time	100 kHz mode	4.0	—	µs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92*	TSU:STO	Stop condition setup time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	CB	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I²C bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

TABLE 17-18: ADC CLOCK PERIOD (T_{AD}) VS. DEVICE OPERATING FREQUENCIES ($V_{DD} \geq 3.0V$, $V_{REF} \geq 2.5V$)

ADC Clock Period (T_{AD})		Device Frequency (F_{OSC})			
ADC Clock Source	**ADCS<2:0>**	**20 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
Fosc/2	000	100 ns	250 ns	500 ns	2.0 μs
Fosc/4	100	200 ns	500 ns	1.0 μs	4.0 μs
Fosc/8	001	400 ns	1.0 μs	2.0 μs	8.0 μs
Fosc/16	101	800 ns	2.0 μs	4.0 μs	16.0 μs
Fosc/32	010	1.6 μs	4.0 μs	8.0 μs	32.0 μs
Fosc/64	110	3.2 μs	8.0 μs	16.0 μs	64.0 μs
Frc	x11	2-6 μs	2-6 μs	2-6 μs	2-6 μs

Legend: Shaded cells should not be used for conversions at temperatures above +125°C.

Note 1: T_{AD} must be between 1.6 μs and 4.0 μs.

TABLE 17-23: OSCILLATOR PARAMETERS FOR PIC16F685/687/689/690-H (High Temp.)

Param No.	Sym.	Characteristic	Frequency Tolerance	Min.	Typ.	Max.	Units	Conditions
OS08	INTOSC	Int. Calibrated INTOSC Freq.(1)	±7.5%	7.4	8.0	8.6	MHz	2.1V ≤ VDD ≤ 5.5V -40°C ≤ TA ≤ 150°C

Note 1: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

TABLE 17-24: WATCHDOG TIMER SPECIFICATIONS FOR PIC16F685/687/689/690-H (High Temp.)

Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
31	TWDT	Watchdog Timer Time-out Period (No Prescaler)	10	20	70	ms	150°C Temperature

TABLE 17-25: BROWN-OUT RESET SPECIFICATIONS FOR PIC16F685/687/689/690-H (High Temp.)

Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
35	VBOR	Brown-Out Reset Voltage	2.0	—	2.3	V	150°C Temperature

TABLE 17-26: COMPARATOR SPECIFICATIONS FOR PIC16F685/687/689/690-H (High Temp.)

Param No.	Sym.	Characteristic	Min.	Typ.	Max.	Units	Conditions
CM01	VOS	Input Offset Voltage	—	±5	±20	mV	(VDD - 1.5)/2

FIGURE 18-8: TYPICAL IDD vs. VDD OVER FOSC (EXTRC MODE)

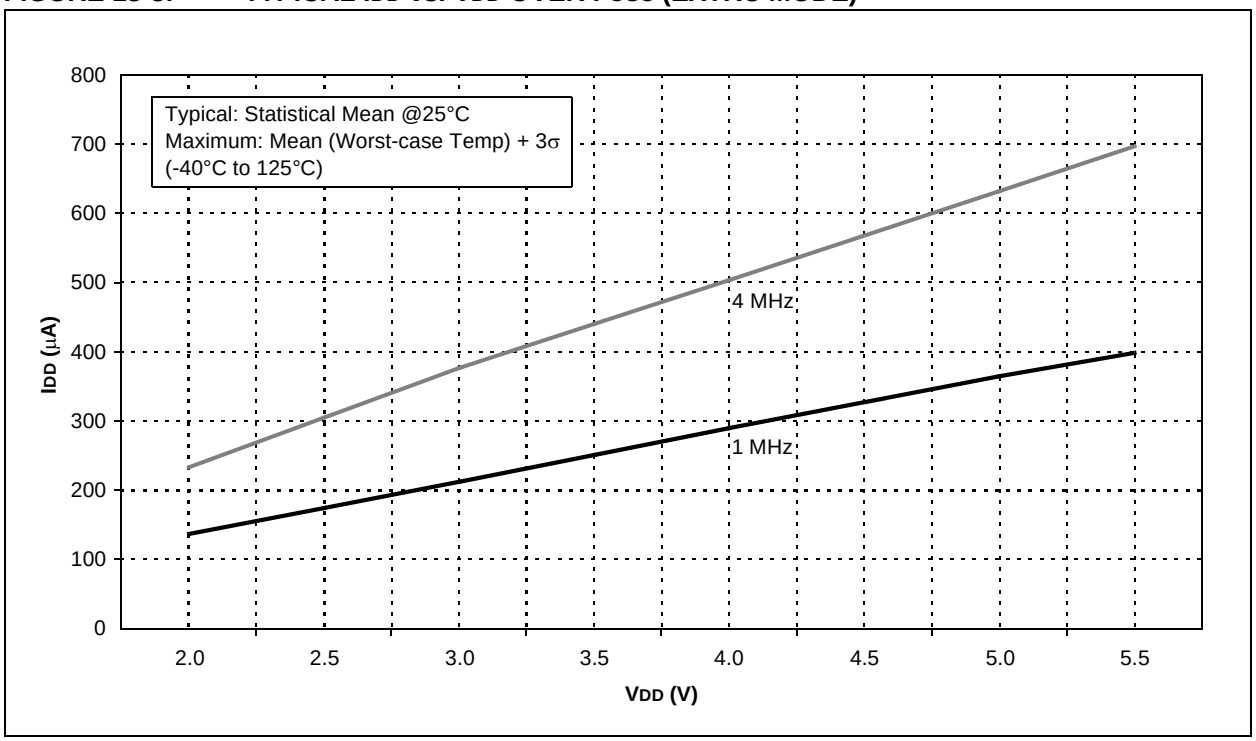


FIGURE 18-9: MAXIMUM IDD vs. VDD OVER FOSC (EXTRC MODE)

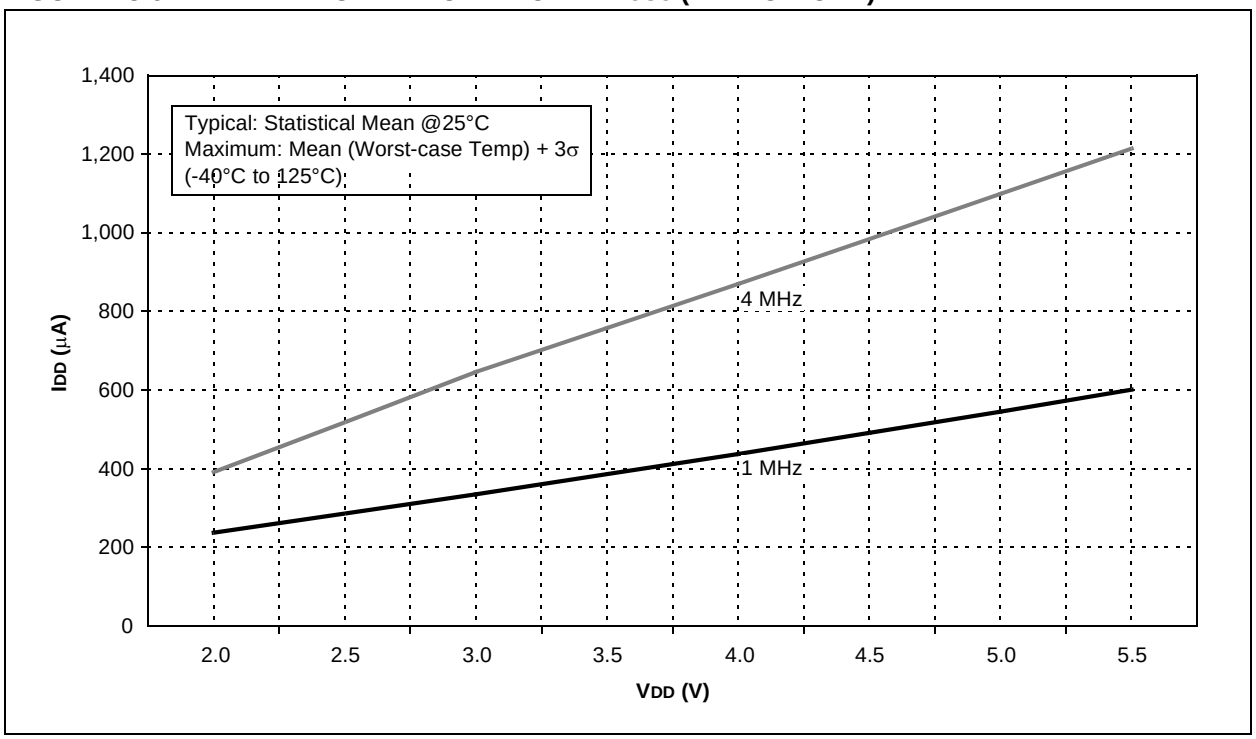


FIGURE 18-48: TYPICAL VP6 REFERENCE VOLTAGE DISTRIBUTION (3V, 125°C)

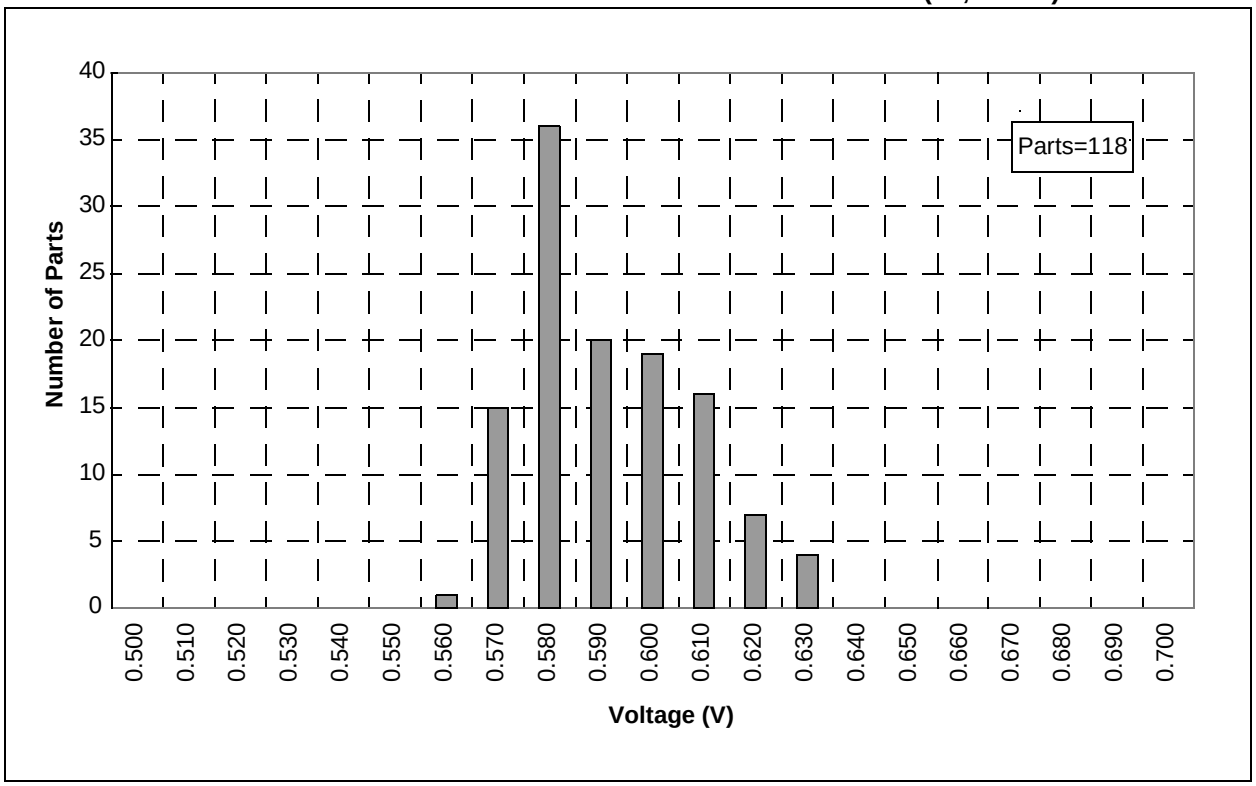
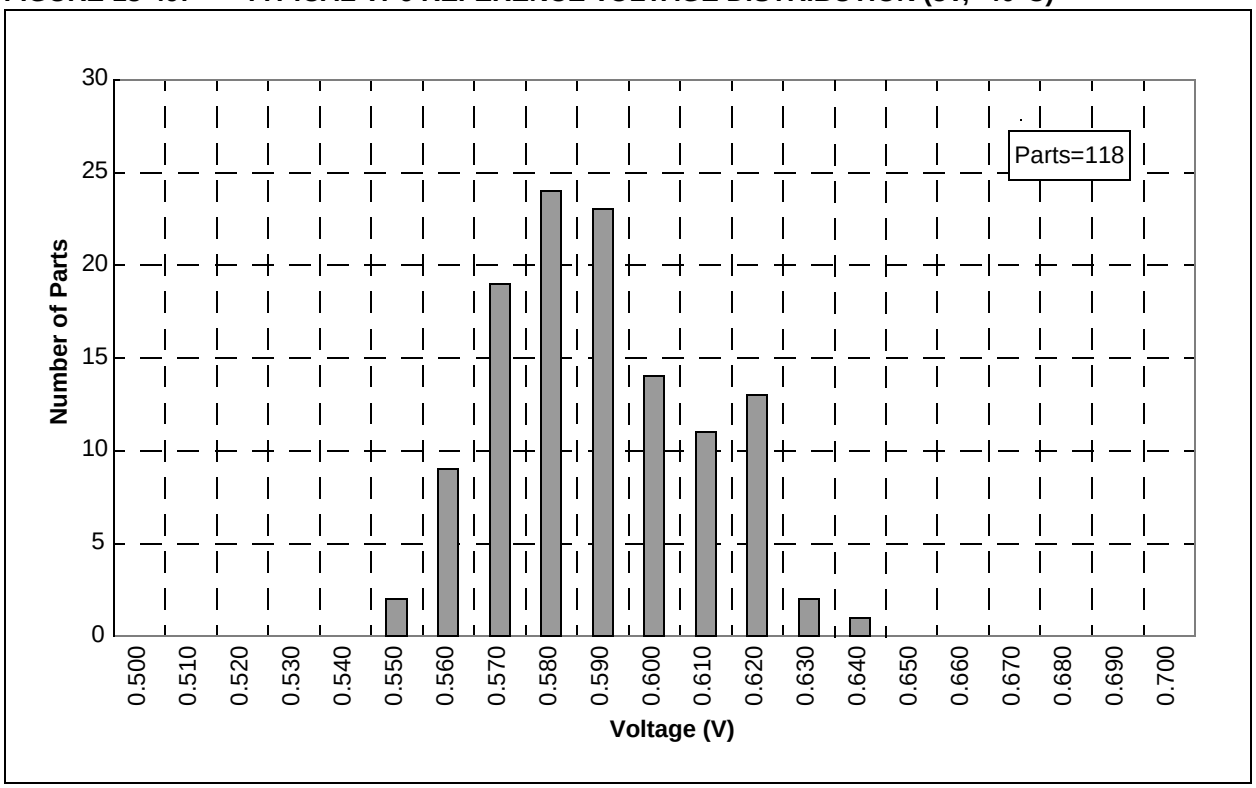


FIGURE 18-49: TYPICAL VP6 REFERENCE VOLTAGE DISTRIBUTION (3V, -40°C)

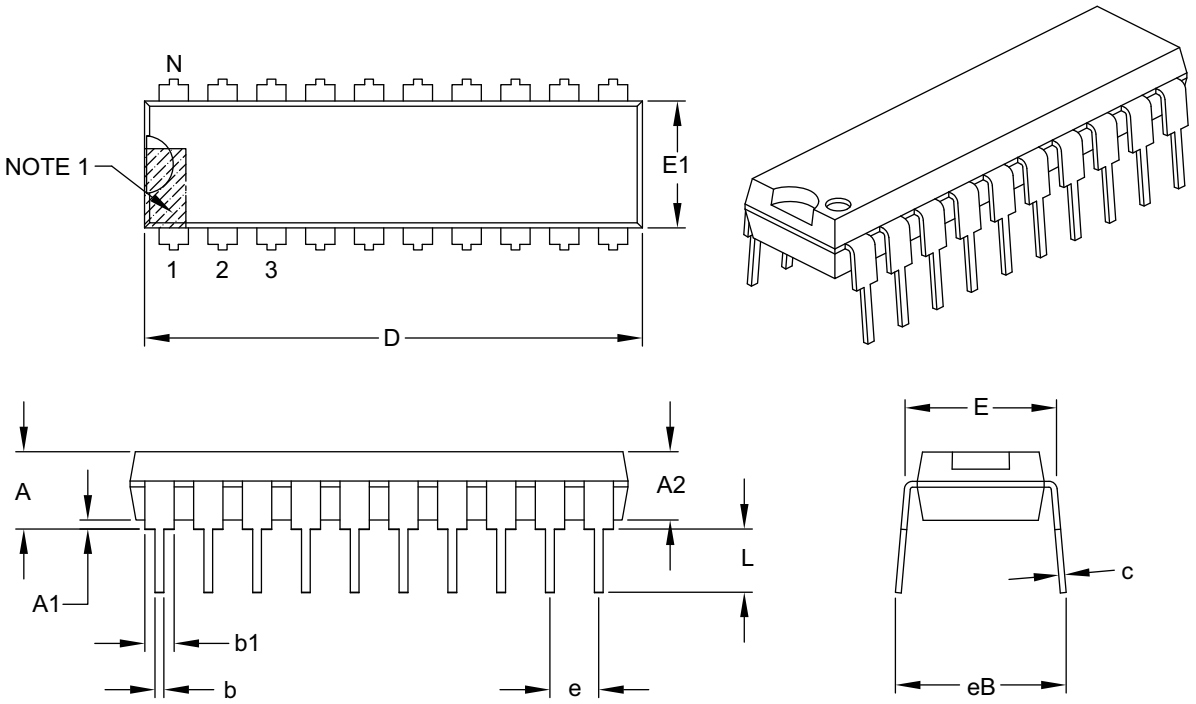


19.2 Package Details

The following sections give the technical details of the packages.

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

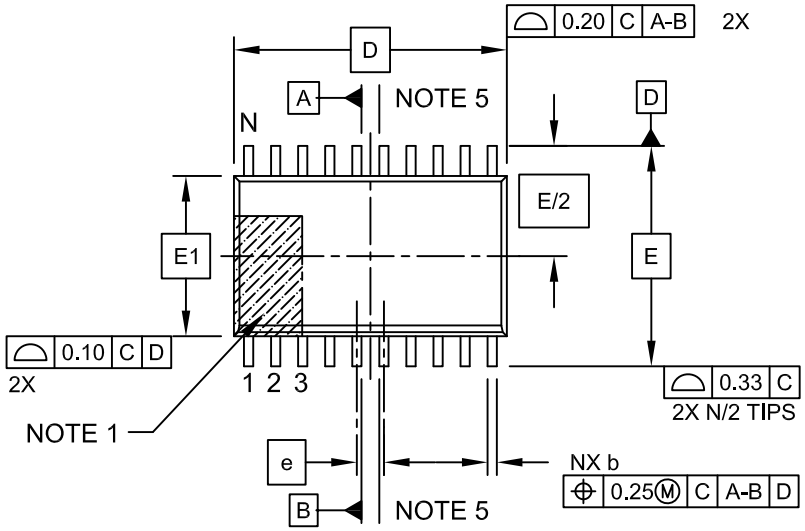
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

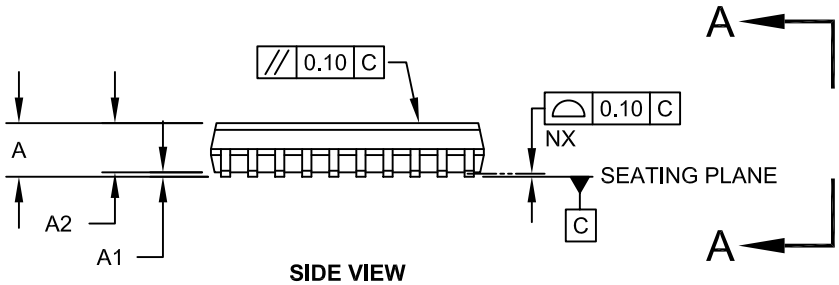
Microchip Technology Drawing C04-019B

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

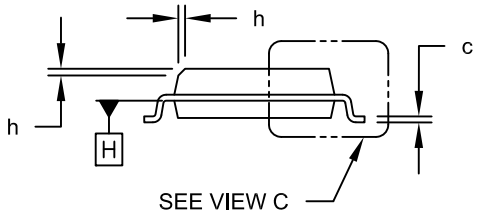
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-094C Sheet 1 of 2